

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A method of manufacturing a contactless smart card including an integrated-circuit chip and an antenna, comprising: producing the antenna [†] from a thermoplastic material loaded with metallic particles, producing metallised protrusions on two contact pads on the chip, ~~said method including the step of and~~ connecting the chip to the antenna by ~~embedding~~ thermocompression to embed the metallised protrusions in a thickness of the antenna, at the time that the chip is connected to the antenna.

2. (Canceled)

3. (Previously Presented) The method according to claim 1, comprising producing the antenna on an insulating substrate having a form factor of the smart card.

4. (Canceled)

5. (Currently Amended) ~~The method according to claim 1,~~ A method of manufacturing a contactless smart card including an integrated-circuit chip and an antenna

comprising producing the antenna from a non-polymerised conductive material, producing metallised protrusions on two contact pads on the chip, and connecting the chip to the antenna by compression to embed the metallised protrusions in a thickness of the antenna, at the time that the chip is connected to the antenna, and ~~further including the step of~~ polymerizing the antenna material by applying heat.

6. (Currently Amended) ~~The method according to claim 1,~~ A method of manufacturing a contactless smart card including an integrated-circuit chip and an antenna comprising producing the antenna from a moist conductive polymer material, producing metallised protrusions on two contact pads on the chip, and connecting the chip [is attached] to the antenna by compression to embed the metallised protrusions in a thickness of the antenna, at the time that the chip is connected to the antenna.

7. (Currently Amended) ~~The method according to claim 1,~~ A method of manufacturing a contactless smart card including an integrated-circuit chip and an antenna comprising producing the antenna from a thermoplastic material loaded with metallic particles, producing metallised protrusions on two contact pads on the chip, and gluing the chip to an insulating sheet having the form factor of a smart card, and ~~wherein the~~ connecting of the chip to the antenna ~~is effected by hot lamination~~ to embed the metallised protrusions in a thickness of the antenna, at the time that the chip is connected to the antenna.

8. (Previously Presented) The method according to claim 1, wherein the metallised protrusions have a substantially conical shape.

9. (New) The method according to claim 5, wherein the metallised protrusions have a substantially conical shape.

10. (New) The method according to claim 6, wherein the metallised protrusions have a substantially conical shape.